

ABSTRACT

To provide a dielectric-layer-provided copper foil or the like for extremely improving the product yield while making the most use of the increase effect of an electric capacity of a thin dielectric layer using the sputtering vapor deposition method.

In the case of dielectric-layer-provided copper foils respectively having a dielectric layer on one side of a copper foil, the dielectric layer 6 is an inorganic-oxide sputter film having a thickness of 1.0 μm or less and formed on the one side of the copper foil in accordance with the sputtering vapor deposition method and the dielectric-layer-provided copper foils for respectively forming a capacitor layer, characterized in that a pit-like defective portion generated on the inorganic-oxide sputter film is sealed by polyimide resin are used.